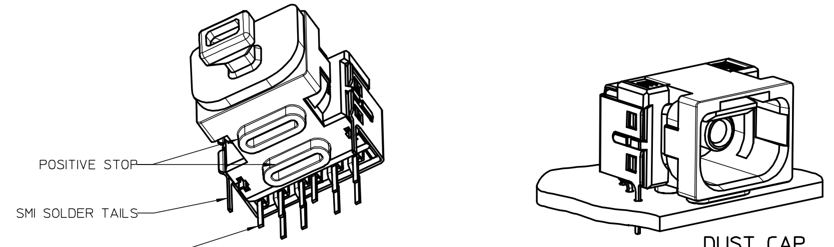
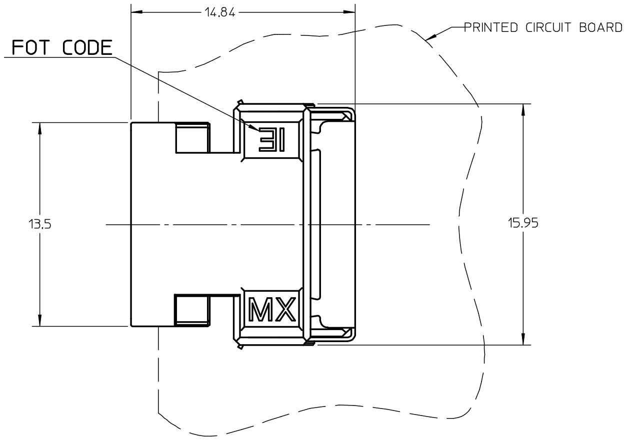
SMI/SMT TRANSCEIVER ASSEMBLY P/N	FOT's TYPE	FOT CODE
1061082100	IEEE-1394/ DIGITAL FDL300K	IE
1061083100	10/100 ETHERNET EDL300K	EL
1061084100	INDUSTRIAL DATA LINK IDL300K	ID

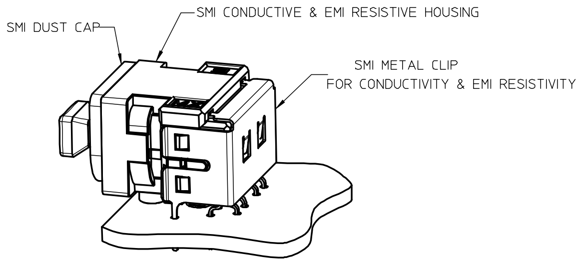


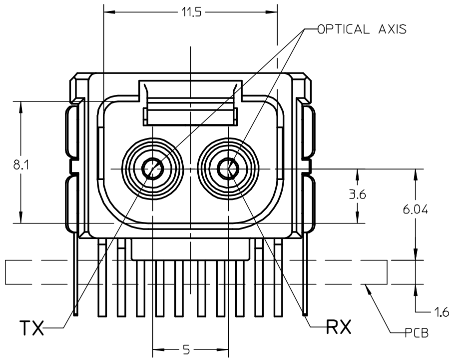
DUST CAP
IS NOT SHOWN

ISOMETRIC VIEWS
SCALE 2.5:1

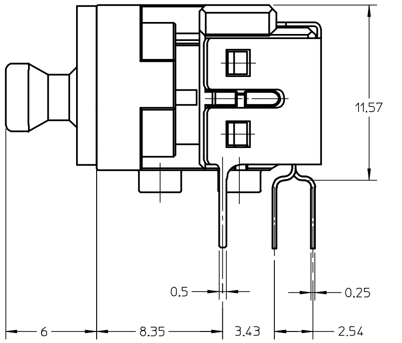


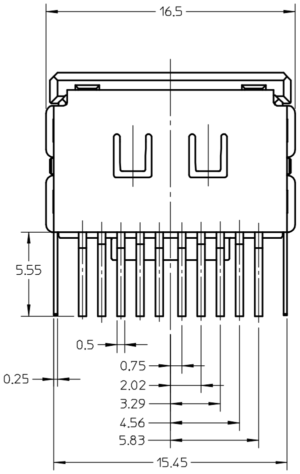
DUST CAP NOT SHOWN

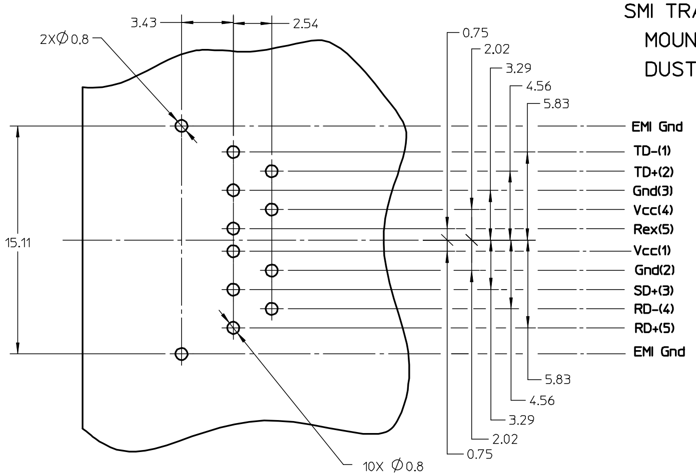




SMI TRANSCEIVER ASSEMBLY
MOUNTED ON THE PCB
DUST CAP NOT SHOWN







RECOMMENDED PCB LAYOUT
DIMENSIONS TOLERANCE: ±0.1mm

NOTES:

1. ALL DIMENSIONS ARE FOR REFERENCE ONLY EXCEPT FOR RECOMMENDED PCB LAYOUT.
2. ATTACHMNET OF THIS COMPONENT TO THE PCB VIA HOT BAR,LASER OR IR SOLDERING.
   RE-FLOW OVEN SOLDERING IS NOT APPROVED AT THIS TIME.

REV	DESCRIPTION
B	ENTER DESCRIPTION EC NO: MF2008-0555 DRWN:SMIGO 2008/06/11 CH'KD: 2008/06/11 APPR:SMIGO 2008/06/26

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± ---	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: 4:1	DESIGN UNITS: METRIC
DRAWN BY: BG	DATE: 09/12/06	THIRD ANGLE PROJECTION
CHECKED BY: SE	DATE: 9/15/06	
APPROVED BY:	DATE:	
MATERIAL NO.: SEE TABLE	DOCUMENT NO.: SD-106108-X100	SHEET NO.: 1 OF 1
SIZE: C		

TITLE
SMI TRANSCEIVER ASSEMBLY
THROUGH- HOLE SOLDERING

molex MOLEX INCORPORATED